

## Avalanche Energy Rated N-Channel Power MOSFETs

2.5A and 3.0A, 350V-400V  
 $r_{DS(on)} = 1.8\Omega$  and  $2.5\Omega$

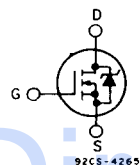
### Features:

- Single pulse avalanche energy rated
- SOA is power-dissipation limited
- Nanosecond switching speeds
- Linear transfer characteristics
- High input impedance

The IRF720R, IRF721R, IRF722R and IRF723R are advanced power MOSFETs designed, tested, and guaranteed to withstand a specified level of energy in the breakdown avalanche mode of operation. These are n-channel enhancement-mode silicon-gate power field-effect transistors designed for applications such as switching regulators, switching converters, motor drivers, relay drivers, and drivers for high-power bipolar switching transistors requiring high speed and low gate-drive power. These types can be operated directly from integrated circuits.

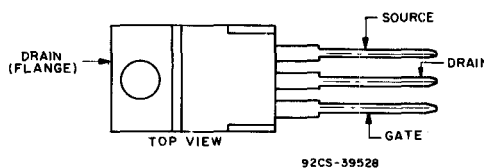
The IRF-types are supplied in the JEDEC TO-220AB plastic package.

### TERMINAL DIAGRAM



### N-CHANNEL ENHANCEMENT MODE

### TERMINAL DESIGNATION



### JEDEC TO-220AB

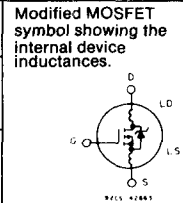
### Absolute Maximum Ratings

Parameter	IRF720R	IRF721R	IRF722R	IRF723R	Units
$V_{DS}$ Drain - Source Voltage ①	400	350	400	350	V
$V_{DGR}$ Drain - Gate Voltage ( $R_{GS} = 20\text{ K}\Omega$ ) ①	400	350	400	350	V
$I_D @ T_C = 25^\circ\text{C}$ Continuous Drain Current	3.0	3.0	2.5	2.5	A
$I_D @ T_C = 100^\circ\text{C}$ Continuous Drain Current	2.0	2.0	1.5	1.5	A
$I_{DM}$ Pulsed Drain Current ③	12	12	10	10	A
$V_{GS}$ Gate - Source Voltage	$\pm 20$				V
$P_D @ T_C = 25^\circ\text{C}$ Max. Power Dissipation	40 (See Fig. 14)				W
Linear Derating Factor	0.32 (See Fig. 14)				W/ $^\circ\text{C}$
$E_{AS}$ Single Pulse Avalanche Energy Rating ④	190				mj
$T_J$ Operating Junction and $T_{stg}$ Storage Temperature Range	-55 to 150				$^\circ\text{C}$
Lead Temperature	300 (0.063 in. (1.6mm) from case for 10s)				$^\circ\text{C}$

**IRF720R, IRF721R  
IRF722R, IRF723R**

**Electrical Characteristics @ T<sub>c</sub> = 25°C (Unless Otherwise Specified)**

Parameter	Type	Min.	Typ.	Max.	Units	Test Conditions
BV <sub>DSS</sub> Drain - Source Breakdown Voltage	IRF720R IRF722R	400	—	—	V	V <sub>GS</sub> = 0V I <sub>D</sub> = 250μA
	IRF721R IRF723R	350	—	—	V	
V <sub>GS(th)</sub> Gate Threshold Voltage	ALL	2.0	—	4.0	V	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250μA
I <sub>GSS</sub> Gate-Source Leakage Forward	ALL	—	—	500	nA	V <sub>GS</sub> = 20V
I <sub>GSS</sub> Gate-Source Leakage Reverse	ALL	—	—	-500	nA	V <sub>GS</sub> = -20V
I <sub>DSS</sub> Zero Gate Voltage Drain Current	ALL	—	—	250	μA	V <sub>DS</sub> = Max. Rating, V <sub>GS</sub> = 0V
		—	—	1000	μA	V <sub>DS</sub> = Max. Rating x 0.8, V <sub>GS</sub> = 0V, T <sub>c</sub> = 125°C
I <sub>D(on)</sub> On-State Drain Current ②	IRF720R IRF721R	3.0	—	—	A	V <sub>DS</sub> > I <sub>D(on)</sub> x R <sub>DS(on)max.</sub> , V <sub>GS</sub> = 10V
	IRF722R IRF723R	2.5	—	—	A	
	IRF720R IRF721R IRF722R IRF723R	—	1.5	1.8	Ω	
R <sub>DS(on)</sub> Static Drain-Source On-State Resistance ②	IRF720R IRF721R	—	1.5	1.8	Ω	V <sub>GS</sub> = 10V, I <sub>D</sub> = 1.5A
IRF722R IRF723R	—	1.8	2.5	Ω		
g <sub>fs</sub> Forward Transconductance ②	ALL	1.0	2.0	—	S(V)	V <sub>DS</sub> > I <sub>D(on)</sub> x R <sub>DS(on)max.</sub> , I <sub>D</sub> = 1.5A
C <sub>iss</sub> Input Capacitance	ALL	—	450	—	pF	V <sub>GS</sub> = 0V, V <sub>DS</sub> = 25V, f = 1.0 MHz See Fig. 10
C <sub>oss</sub> Output Capacitance	ALL	—	100	—	pF	
C <sub>rss</sub> Reverse Transfer Capacitance	ALL	—	20	—	pF	V <sub>DD</sub> ≈ 0.5BV <sub>DSS</sub> , I <sub>D</sub> = 1.5A, Z <sub>θ</sub> = 50Ω See Fig. 17 (MOSFET switching times are essentially independent of operating temperature.)
t <sub>D(on)</sub> Turn-On Delay Time	ALL	—	20	40	ns	
t <sub>r</sub> Rise Time	ALL	—	25	50	ns	
t <sub>D(off)</sub> Turn-Off Delay Time	ALL	—	50	100	ns	
t <sub>f</sub> Fall Time	ALL	—	25	50	ns	V <sub>GS</sub> = 10V, I <sub>D</sub> = 4.0A, V <sub>DS</sub> = 0.8V Max. Rating. See Fig. 18 for test circuit. (Gate charge is essentially independent of operating temperature.)
Q <sub>g</sub> Total Gate Charge (Gate-Source Plus Gate-Drain)	ALL	—	12	15	nC	
Q <sub>gs</sub> Gate-Source Charge	ALL	—	6.0	—	nC	
Q <sub>gd</sub> Gate-Drain ("Miller") Charge	ALL	—	6.0	—	nC	
L <sub>D</sub> Internal Drain Inductance	ALL	—	3.5	—	nH	Measured from the contact screw on tab to center of die.
		—	4.5	—	nH	
L <sub>S</sub> Internal Source Inductance	ALL	—	7.5	—	nH	Measured from the source lead, 6mm (0.25 in.) from package to source bonding pad.

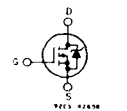


**Thermal Resistance**

R <sub>thJC</sub> Junction-to-Case	ALL	—	—	3.12	°C/W	
R <sub>thCS</sub> Case-to-Sink	ALL	—	1.0	—	°C/W	Mounting surface flat, smooth, and greased.
R <sub>thJA</sub> Junction-to-Ambient	ALL	—	—	80	°C/W	Free Air Operation

**Source-Drain Diode Ratings and Characteristics**

I <sub>S</sub> Continuous Source Current (Body Diode)	IRF720R IRF721R	—	—	3.0	A	Modified MOSFET symbol showing the integral reverse P-N junction rectifier.
	IRF722R IRF723R	—	—	2.5	A	
I <sub>SM</sub> Pulse Source Current (Body Diode) ③	IRF720R IRF721R	—	—	12	A	T <sub>c</sub> = 25°C, I <sub>S</sub> = 3.0A, V <sub>GS</sub> = 0V
	IRF722R IRF723R	—	—	10	A	
	IRF720R IRF721R IRF722R IRF723R	—	—	1.5	V	
t <sub>rr</sub> Reverse Recovery Time	ALL	—	450	—	ns	T <sub>J</sub> = 150°C, I <sub>F</sub> = 3.0A, dI <sub>F</sub> /dt = 100A/μs
Q <sub>RR</sub> Reverse Recovered Charge	ALL	—	3.1	—	μC	T <sub>J</sub> = 150°C, I <sub>F</sub> = 3.0A, dI <sub>F</sub> /dt = 100A/μs
t <sub>on</sub> Forward Turn-on Time	ALL	Intrinsic turn-on time is negligible. Turn-on speed is substantially controlled by L <sub>S</sub> + L <sub>D</sub> .				



① T<sub>J</sub> = 25°C to 150°C.

② Pulse Test: Pulse width ≤ 300μs, Duty Cycle ≤ 2%.

③ Repetitive Rating: Pulse width limited by max. junction temperature. See Transient Thermal Impedance Curve (Fig. 5).

④ V<sub>DD</sub> = 50V, starting T<sub>J</sub> = 25°C, L = 31 mH, R<sub>gs</sub> = 50Ω, I<sub>peak</sub> = 3.3A. See figures 15, 16.

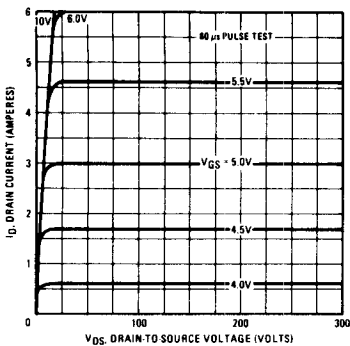


Fig. 1 - Typical Output Characteristics

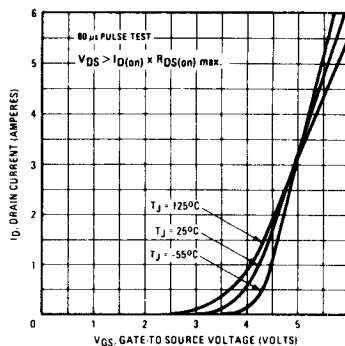


Fig. 2 - Typical Transfer Characteristics

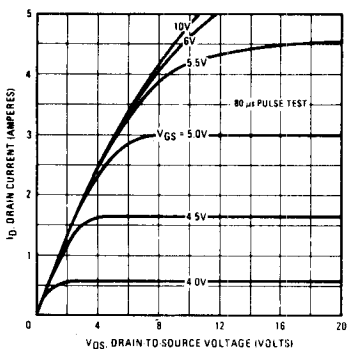


Fig. 3 - Typical Saturation Characteristics

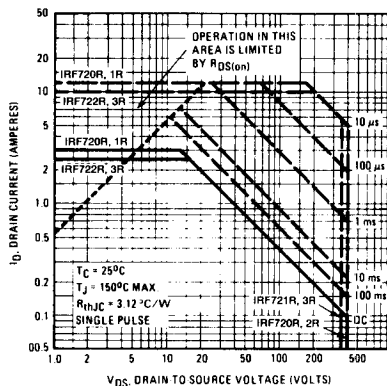


Fig. 4 - Maximum Safe Operating Area

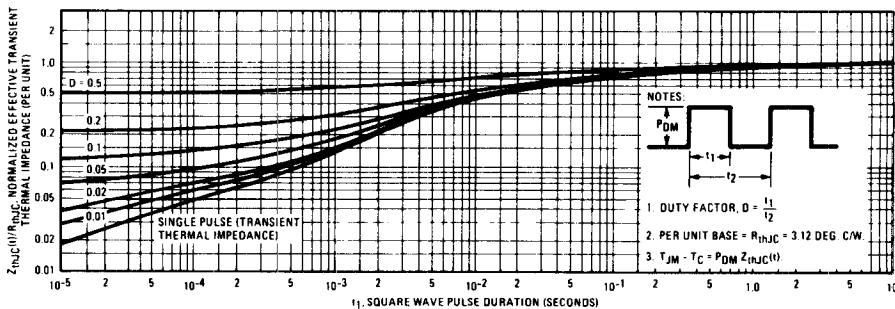


Fig. 5 - Maximum Effective Transient Thermal Impedance, Junction-to-Case Vs. Pulse Duration

IRF720R, IRF721R  
IRF722R, IRF723R

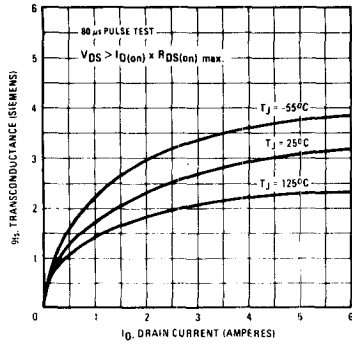


Fig. 6 - Typical Transconductance Vs. Drain Current

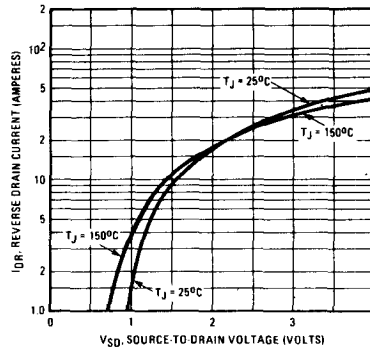


Fig. 7 - Typical Source-Drain Diode Forward Voltage

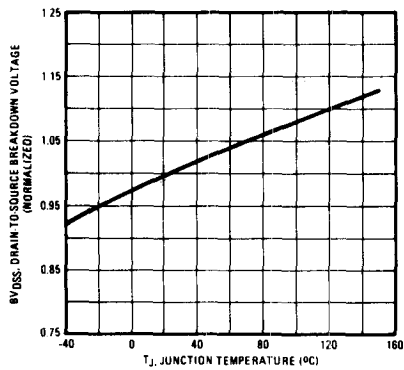


Fig. 8 - Breakdown Voltage Vs. Temperature

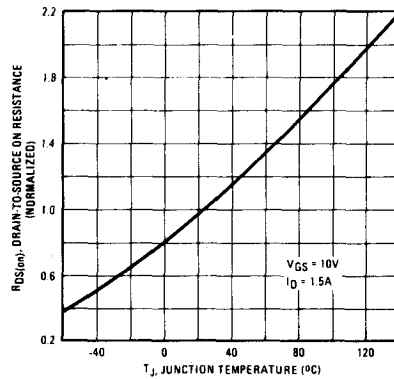


Fig. 9 - Normalized On-Resistance Vs. Temperature

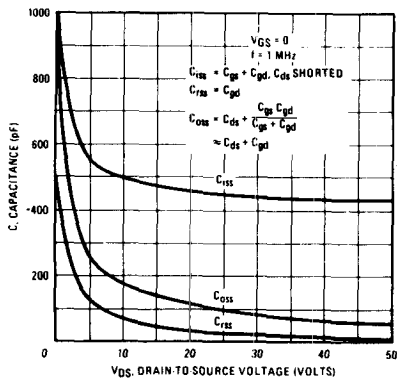


Fig. 10 - Typical Capacitance Vs. Drain-to-Source Voltage

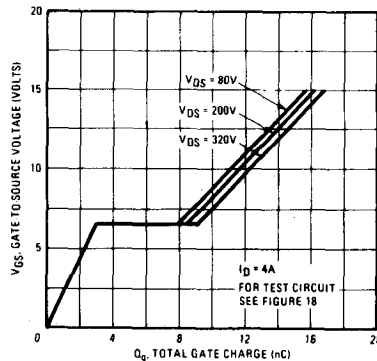


Fig. 11 - Typical Gate Charge Vs. Gate-to-Source Voltage

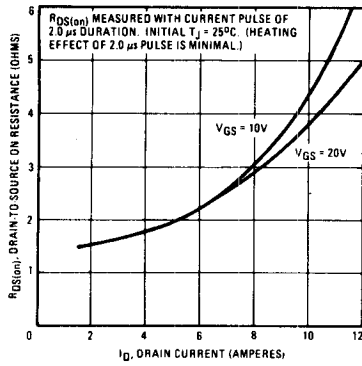


Fig. 12 - Typical On-Resistance Vs. Drain Current

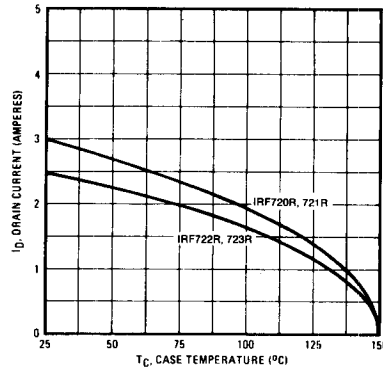


Fig. 13 - Maximum Drain Current Vs. Case Temperature

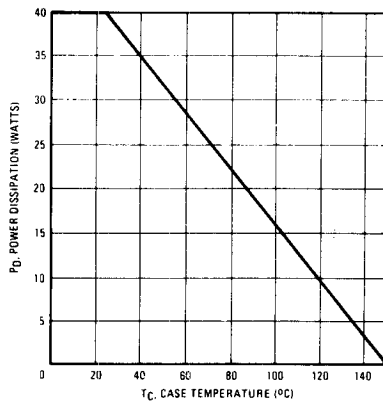


Fig. 14 - Power Vs. Temperature Derating Curve

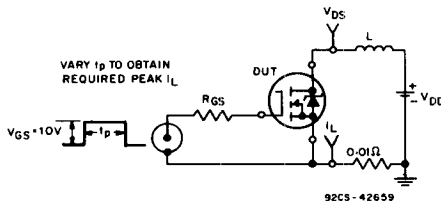


Fig. 15 - Unclamped Energy Test Circuit

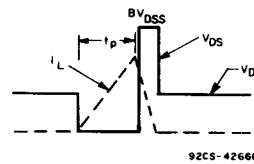


Fig. 16 - Unclamped Energy Waveforms

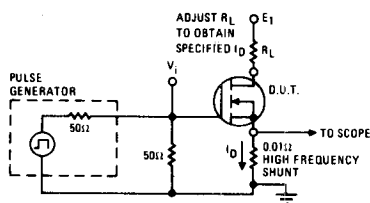


Fig. 17 - Switching Time Test Circuit

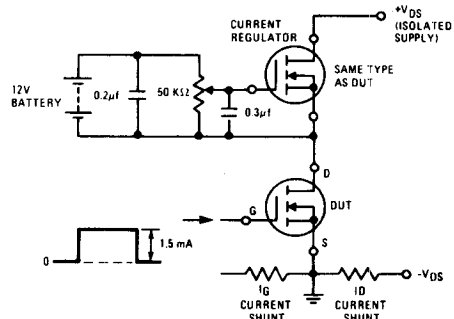


Fig. 18 - Gate Charge Test Circuit